PCN Number:	20170315000A	PCN Date:	Mar 22, 2017
Title:	Wafer Diameter Change for Select Devices in the LBC3S Process at DL-LIN		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Jun 22, 2017	Estimated Sample availability:	Date Provided at Sample request

Change Type:

☐	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☒	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

The purpose of this Rev A PCN is to add additional devices to the product affected section of this notification. Additional devices are shown as bold with a yellow highlight.

This change notification is to announce a wafer diameter change only for select devices in the LBC3S process at DL-LIN. This is not a fab site change.

Current	New
Site/Process/Wafer Diameter	Site/Process/**Wafer Diameter**
DL-LIN/LBC3S Process/150mm	DL-LIN/LBC3S Process/**200mm**

The LBC3 process is a mature process which has been successfully running production since 02/2000 at DL-LIN.

Reason for Change:

Continuity of supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Note: This is not a fab site change. The 6" line and 8" line are in the same location.

Chip Site	Chip site code (20L)	Chip country code (21L)	Chip Site City
DL-LIN	**DLN**	**USA**	**Dallas**

Sample Product Shipping Label (not actual product label)

Product Affected:

TLC084CD	**TLC084CNE4**	**TLC084IDG4**	TLC084IPWPR
TLC084CDG4	TLC084CPWP	TLC084IDR	**TLC084IPWPRG4**

TLC084CDR	TLC084CPWPR	**TLC084IDRG4**	TLC085CN
TLC084CDRG4	TLC084ID	TLC084IPWP	TLC085CPWP
TLC084CN			

Qualification Report

Conversion of select devices from 150mm wafers to 200mm wafers in DFAB

Approve Date 05-Nov-2015

Product Attributes

Attributes	Qual Device: SN65HVD1176D	Qual Device: SN65HVD22P	Qual Device: SN65HVD234D	Qual Device: TLC085AIPWP	Qual Device: TLV2252ID	Qual Device: TLV2254IN	Qual Device: TLV2262ID	Qual Device: TLV2372IDGK	Qual Device: TLV2463IDGS	Qual Device: UCC27424D	QBS Process Reference: SN104605PN
Assembly Site	FMX	FMX	FMX	TAI	FMX	FMX	FMX	HNT	-	FMX	TAI
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	DFAB	DFAB	DFAB	DFAB	DFAB	DFAB	DFAB	DFAB	DFAB	DFAB	DFAB
Wafer Process	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S

- QBS: Qual By Similarity
- Qual Devices qualified at LEVEL1-260C: SN65HVD1176D, SN65HVD234D, TLV2372IDGK, TLV2262ID, TLV2252ID, UCC27424D, TLV2463IDGS,
- Qual Devices qualified at Not Classified: SN65HVD22P, TLV2254IN
- Qual Device TLC085AIPWP is qualified at LEVEL2-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: SN65HVD1176D	Qual Device: SN65HVD22P	Qual Device: SN65HVD234D	Qual Device: TLC085AIPWP	Qual Device: TLV2252ID	Qual Device: TLV2254IN	Qual Device: TLV2262ID	Qual Device: TLV2372IDGK	Qual Device: TLV2463IDGS	Qual Device: UCC27424D	QBS Process Reference: SN104605PN
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	-
HAST	Biased Hast, 130C/85%RH	96 Hours	-	-	-	-	-	-	-	-	-	-	3/231/0
HBM	ESD - HBM	2500 V	-	-	-		1/3/0	1/3/0	-	-	-	-	-
HBM	ESD - HBM	3000 V	-	-	-	1/3/0	-	-	1/3/0	-	-	-	-
HBM	ESD - HBM	4000 V	1/3/0	-	1/3/0	-	-	-	-	1/3/0	1/3/0	1/3/0	-
HBM	ESD - HBM	5000 V	-	1/3/0	-	-	-	-	-	-	-	-	-
HBM	ESD - HBM (Bus & Ground pins)	10000V	1/3/0	-	-	-	-	-	-	-	-	-	-
HBM	ESD - HBM (Pin 7, 6 and gnd)	16000 V	-	1/3/0	1/3/0	-	-	-	-	-	-	-	-
CDM	ESD - CDM	1500 V	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	-
HTOL	Life Test 155C	1000 Hours	-	-	-	-	-	-	-	-	-	-	3/231/0
LU	Latch-up	(per JESD78)	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	-
TS	Thermal Shock, -65/150C	500 Cycles	-	-	-	-	-	-	-	-	-	-	3/231/0
WBP	Bond Pull	Wires	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	-	-	1/76/0	3/228/0
WBS	Ball Bond Shear	Wires	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	-	-	1/76/0	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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